Filename: PMP7030 REV_A_bom.xls
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PMP7030 REV_A BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	100p	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	0603	C1608X7R1H101K	muRata
1	C2	47uF	Capacitor, Alum Electrolytic 450 V, ±20%	16.00 mm Dia	EKXJ451ESS470ML25S	Nippon Chemi-Con
1	C3	0.01uF	Capacitor, Ceramic, 250V, C0G, 10%	1206	Std	TDK
1	C6	470uF	Capacitor, Aluminum, 35V, 105C, 20%	10mm	EKZM350ESS471MJ16S	Nippon Chemi-con
1	C7	1uF	Capacitor, Ceramic, Low Inductance, 25V, X5R, 10%	0603	GRM39yyyxxxKvvvA	muRata
1	C8	0.33uF	Capacitor, Ceramic, 50V, X7R	0805	STD	STD
1	C10	47uF	Capacitor, Aluminum Electrolytic, 25V	0.200 * 0.435 inch	25V ZL 47uF 5 X 11	Rubycon
1	C11	1500pF	CAP, CERM DISC Y1, 250Vac, 20%	.500 X .310	ECKDNA152ME	Panasonic
1	C12	2.2nF	Capacitor, Ceramic, Low Inductance, 50V, X7R, 10%	0603	C1608X7R1H103K	muRata
1	C13	0.22 uF	Capacitor, Film, 250VAC, 20%	0.689 x 0.217	ECQU2A224MV	Panasonic
1	C14	22pF	Capacitor, Ceramic, 1000V, COG, -55C...+125C]	1206	Std	Std
1	C15	470pF	Capacitor, Ceramic, 250V, X7R, 10%	0805	Std	Std
2	C4 C9	0.1uF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	0603	C1608X7R1H104K	muRata
3	C5 C16 C100	10uF	Capacitor, Ceramic, 25V, X7R, 10%	1210	C3225X5R1E106K	TDK
1	D1	KBP06G	Diode, Bridge Rectifier, 1.5A, 600V	0.580 x 0.145 inch	DF06S	Diodes
1	D2	18V	Diode, Zener, 18V	SMA	1SMA5931BT3	ON Semi
1	D3	MMSD914	Diode, Switching, 100-V, 200-mA, 225-mW	SOD-123	MMSD914T1	On Semi
1	D4	MURA160T3	Diode, Rectifier, 1A, 600V	SMA	MURA160T3	ON Semiconductor
1	D5	BAS40-04T-7-F	Diode, Dual Series, 40V, 200mA	SOT23	BAS40-04T-7-F	Diodes
1	D6	MBR0520L	Diode, Schottky, 0.5A, 20V	SOD-123	MBR0520L	Fairchild
1	D7	MBRB20100CT	Diode, Dual Schottky, 20-A, 100-V	D2PAK	MBRB20100CT	ON Semi
1	F1	2A	Fuse, TR5 Time Lag, 2A, 250V	0.335	3831200000	Littlefuse
1	L1	10uH	Inductor, Power, 4.2A, 40 milli-Ohms	0.350 x 0.300 inch	RFB0807-100L	Coilcraft
1	L2	10 mH	Inductor, Common Mode , 0.7A, 0.65 Ohm	12.5x18 mm	RDS18V-0,7-10 049.670	Kaschke
1	L3	60 Ohm @ 100MHz	Ferrite Bead, High Current, 60-Ohm @ 100MHz, 6A, 10-milliohm	1806	BLM41PG600SN1	Murata
1	L4	470uH	Inductor, SMT, 0.3A, 905milliohm	0.51x 0.37 inch	DO3340P-474ML	Coilcraft
1	Q1	STD11NM60N	MOSFET, N-ch, 650-V, 10-A, 450-milliOhms	DPAK	STD11NM60N	ST
1	R1	3.3	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R6	51.1K	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R7	47k	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R8	20K	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R9	13.7K	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R11	180K	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R13	1K	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R14	2.2	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R15	68K	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R16	10	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R17	0	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	R18	47	Resistor, Chip, 1/10W, 1%	0805	CRCW0805-xxxx-F	Vishay
1	R19	1k	Resistor, Chip, 1-W, 5%	2512	Std	Std
1	R20	100	Resistor, Chip, 1-W, 5%	2512	Std	Std
1	R21	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
2	R2 R12	100k	Resistor, Chip, 1-W, 5%	2512	Std	Std

3	R22-24	2.2M	Resistor, Chip, 1/10W, 1%	0805	CRCW0805-xxxx-F	Vishay
2	R3-4	10K	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
2	R5 R10	100K	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
1	RT1	2.5	Thermistor,	0.236 X 0.512 inch	B57237S0259M000	Epcos
1	T1	330 uH	Transformer, ±10%	26.5X32 mm	SP-EFS25-13	Kaschke
1	TP1	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
3	TP2-4	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI
1	U2	UCC28610D	IC, Flyback Green-Mode Controller	SO8	UCC28610D	TI
1	U3	TCMT1107	IC, Photocoupler	MF4	H11A817A	Vishay

Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
2. These assemblies must be clean and free from flux and all contaminants.
   Use of no clean flux is not acceptable.
3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
4. Ref designators marked with an asterisk ('**') cannot be substituted.
   All other components can be substituted with equivalent MFG's components.

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